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December 2013

## FDPF8N50NZU

## N-Channel UniFET<sup>TM</sup> II Ultra FRFET<sup>TM</sup> MOSFET 500 V, 6.5 A, 1.2 $\Omega$

#### **Features**

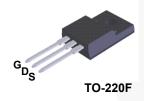
- $R_{DS(on)} = 1.0 \Omega$  (Typ.) @  $V_{GS} = 10 \text{ V}$ ,  $I_D = 3.25 \text{ A}$
- Low Gate Charge (Typ. 14 nC)
- Low C<sub>rss</sub> (Typ. 5 pF)
- 100% Avalanche Tested
- · Improved dv/dt Capability
- · ESD Improved Capability
- · RoHS Compliant

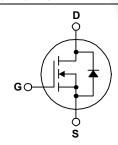
### **Applications**

- LCD/LED TV
- Lighting
- · Uninterruptible Power Supply
- AC-DC Power Supply

## Description

UniFET™ II MOSFET is Fairchild Semiconductor's high voltage MOSFET family based on advanced planar stripe and DMOS technology. This advanced MOSFET family has the smallest on-state resistance among the planar MOSFET, and also provides superior switching performance and higher avalanche energy strength. In addition, internal gate-source ESD diode allows UniFET II MOSFET to withstand over 2kV HBM surge stress. UniFET II Ultra FRFET™ MOSFET has much superior body diode reverse recovery performance. Its t<sub>rr</sub> is less than 50nsec and the reverse dv/dt immunity is 20V/nsec while normal planar MOSFETs have over 200nsec and 4.5V/nsec respectively. Therefore UniFET II Ultra FRFET MOSFET can remove additional component and improve system reliability in certain applications that require performance improvement of the MOSFET's body diode. This device family is suitable for switching power converter applications such as power factor correction (PFC), flat panel display (FPD) TV power, ATX and electronic lamp ballasts.





#### **Absolute Maximum Ratings** T<sub>C</sub> = 25°C unless otherwise noted.

Symbol		Parameter		FDPF8N50NZU	Unit
V <sub>DSS</sub>	Drain to Source Voltage			500	V
V <sub>GSS</sub>	Gate to Source Voltage			±25	V
	Drain Current	- Continuous (T <sub>C</sub> = 25°C)		6.5*	
ID	Diam Current	- Continuous (T <sub>C</sub> = 100°C)		3.9*	Α
I <sub>DM</sub>	Drain Current	- Pulsed	(Note 1)	26*	Α
E <sub>AS</sub>	Single Pulsed Avalanche I	Energy	(Note 2)	80	mJ
I <sub>AR</sub>	Avalanche Current (Note		(Note 1)	6.5	Α
E <sub>AR</sub>	Repetitive Avalanche Energy (Note		(Note 1)	13	mJ
dv/dt	Peak Diode Recovery dv/d	dt	(Note 3)	20	V/ns
D	Dower Dissination	(T <sub>C</sub> = 25°C)		40	W
$P_D$	Power Dissipation	- Derate Above 25°C		0.32	W/°C
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temperature Range			-55 to +150	°C
T <sub>L</sub>	Maximum Lead Temperat 1/8" from Case for 5 Seco	•		300	°C

<sup>\*</sup>Drain current limited by maximum junction temperature

#### **Thermal Characteristics**

Symbol	Parameter	FDPF8N50NZU	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max.	3.1	
$R_{\theta CS}$	Thermal Resistance, Case to Sink, Typ.	0.5	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient, Max.	62.5	

## **Package Marking and Ordering Information**

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FDPF8N50NZU	FDPF8N50NZU	TO-220F	Tube	N/A	N/A	50 units

## Electrical Characteristics T<sub>C</sub> = 25°C unless otherwise noted.

Parameter	Test Conditions	Min.	Тур.	Max.	Unit
cteristics					
Drain to Source Breakdown Voltage	$I_D = 250 \mu A$ , $V_{GS} = 0 V$ , $T_C = 25 ^{\circ} C$	500	-	-	V
Breakdown Voltage Temperature Coefficient	I <sub>D</sub> = 250μA, Referenced to 25°C	-	0.5	-	V/°C
Zoro Gato Voltago Drain Current	V <sub>DS</sub> = 500V, V <sub>GS</sub> = 0V	-	-	25	
Zelo Gate Voltage Diain Current	$V_{DS} = 400V, T_{C} = 125^{\circ}C$	-	-	250	μΑ
Gate to Body Leakage Current	$V_{GS} = \pm 25V, V_{DS} = 0V$	-	-	±10	μΑ
	Drain to Source Breakdown Voltage Breakdown Voltage Temperature Coefficient Zero Gate Voltage Drain Current	CteristicsDrain to Source Breakdown Voltage $I_D = 250\mu A$ , $V_{GS} = 0V$ , $T_C = 25^{\circ}C$ Breakdown Voltage Temperature Coefficient $I_D = 250\mu A$ , Referenced to $25^{\circ}C$ Zero Gate Voltage Drain Current $V_{DS} = 500V$ , $V_{GS} = 0V$ $V_{DS} = 400V$ , $V_{CS} = 125^{\circ}C$			

#### **On Characteristics**

V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = 250 \mu A$	3.0	-	5.0	V
R <sub>DS(on)</sub>	Static Drain to Source On Resistance	V <sub>GS</sub> = 10V, I <sub>D</sub> = 4A	-	1.0	1.2	Ω
9 <sub>FS</sub>	Forward Transconductance	$V_{DS} = 20V, I_{D} = 4A$	-	6.3	-	S

## **Dynamic Characteristics**

C <sub>iss</sub>	Input Capacitance	V 05V V 0V	-	565	735	pF
C <sub>oss</sub>	Output Capacitance	$V_{DS} = 25V, V_{GS} = 0V$ f = 1MHz		80	105	pF
C <sub>rss</sub>	Reverse Transfer Capacitance	T = TIVITIZ	- \	5	8	pF
Q <sub>g(tot)</sub>	Total Gate Charge at 10V	V <sub>DC</sub> = 400V I <sub>D</sub> = 6.5A	-	14	18	nC
Q <sub>gs</sub>	Gate to Source Gate Charge	$V_{DS} = 400V, I_{D} = 6.5A$ $V_{GS} = 10V$	-	4	-	nC
$Q_{gd}$	Gate to Drain "Miller" Charge	(Note 4)	-	6	-	nC

## **Switching Characteristics**

t <sub>d(on)</sub>	Turn-On Delay Time	$V_{DD} = 250V, I_D = 6.5A,$	-	17	45	ns
t <sub>r</sub>	Turn-On Rise Time	$V_{GS} = 10V, R_G = 25\Omega$	-	34	80	ns
t <sub>d(off)</sub>	Turn-Off Delay Time		-	43	95	ns
t <sub>f</sub>	Turn-Off Fall Time	(Note 4)	- /	27	60	ns

#### **Drain-Source Diode Characteristics**

Is	Maximum Continuous Drain to Source Diode Forward Current			-	6.5	Α
I <sub>SM</sub>	Maximum Pulsed Drain to Source Diode Forward Current			-	26	Α
$V_{SD}$	Drain to Source Diode Forward Voltage	$V_{GS} = 0V, I_{SD} = 6.5A$	-	-	1.6	V
t <sub>rr</sub>	Reverse Recovery Time	V <sub>GS</sub> = 0V, I <sub>SD</sub> = 6.5A	-	50	-	ns
Q <sub>rr</sub>	Reverse Recovery Charge	$dI_F/dt = 100A/\mu s$	-	0.05	_	μС

#### Notes

- ${\bf 1.}\ {\bf Repetitive}\ {\bf rating:}\ {\bf pulse-width}\ {\bf limited}\ {\bf by}\ {\bf maximum}\ {\bf junction}\ {\bf temperature}.$
- 2. L = 3.8 mH, I<sub>AS</sub> = 6.5 A, V<sub>DD</sub> = 50 V, R<sub>G</sub> = 25  $\Omega$ , starting T<sub>J</sub> = 25°C.
- $3.\text{I}_{SD} \leq 6.5 \text{ A, di/dt} \leq 200 \text{ A/}\mu\text{s, V}_{DD} \leq \text{BV}_{DSS}, \text{ starting T}_{J} = 25^{\circ}\text{C}.$
- 4. Essentially independent of operating temperature typical characteristics.

## **Typical Performance Characteristics**

Figure 1. On-Region Characteristics

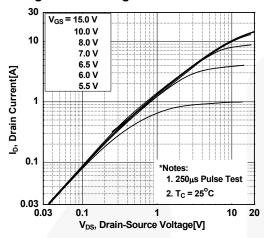


Figure 3. On-Resistance Variation vs.

Drain Current and Gate Voltage

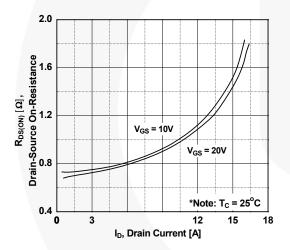


Figure 5. Capacitance Characteristics

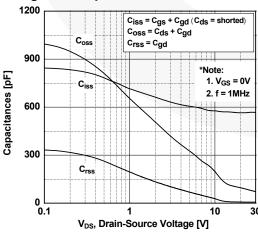


Figure 2. Transfer Characteristics

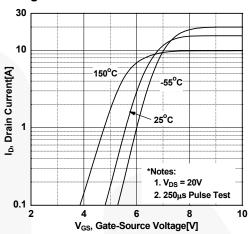
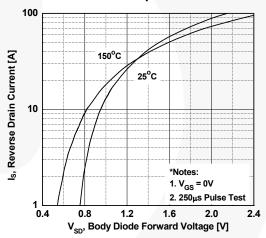
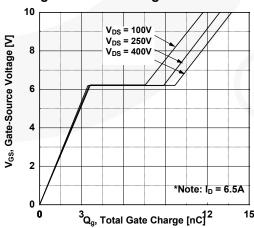


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature



**Figure 6. Gate Charge Characteristics** 



## **Typical Performance Characteristics** (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

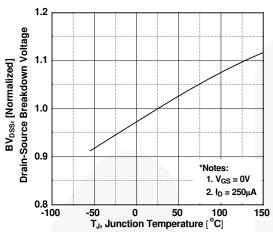


Figure 8. Maximum Safe Operating Area

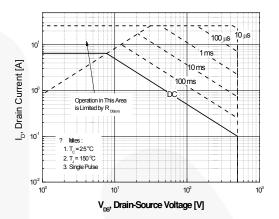


Figure 9. Maximum Drain Current vs. Case Temperature

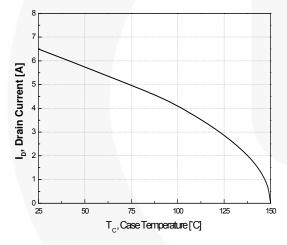
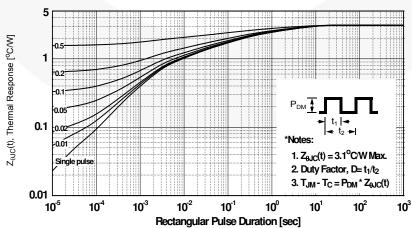


Figure 10. Transient Thermal Response Curve



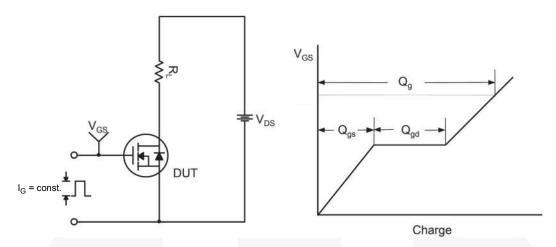


Figure 11. Gate Charge Test Circuit & Waveform

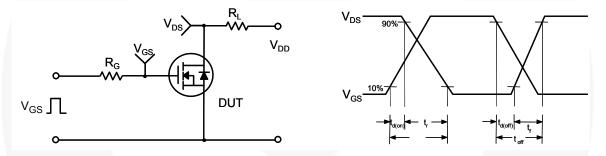


Figure 12. Resistive Switching Test Circuit & Waveforms

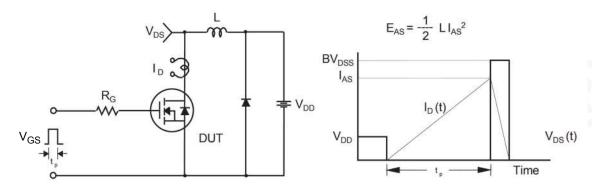


Figure 13. Unclamped Inductive Switching Test Circuit & Waveforms

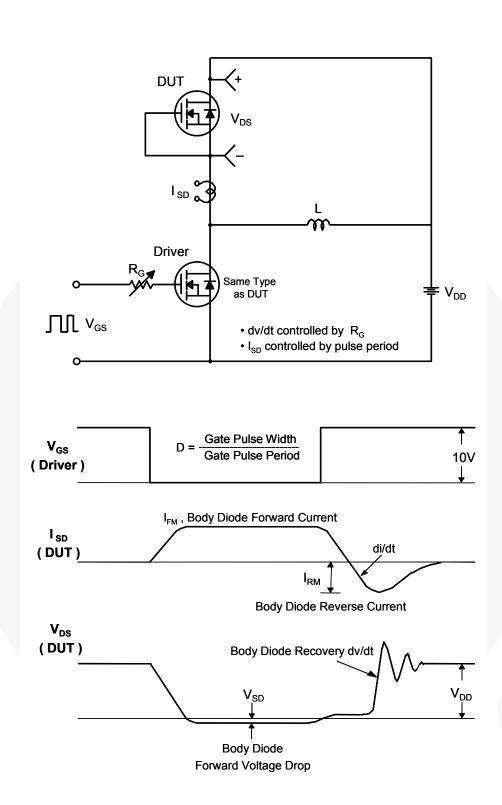


Figure 14. Peak Diode Recovery dv/dt Test Circuit & Waveforms

#### **Mechanical Dimensions**

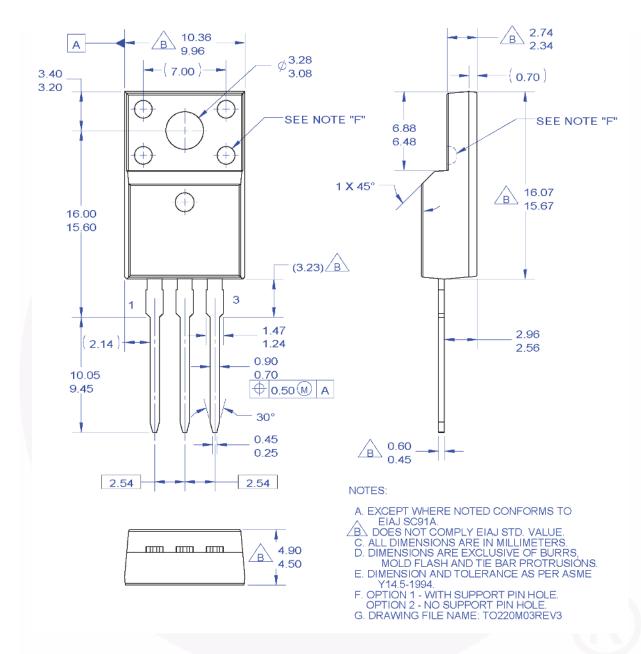


Figure 15. TO220, Molded, 3-Lead, Full Pack, EIAJ SC91, Straight Lead

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